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A+ Server 2123BT-HNR(Complete System Only)



	Integrated Board	Key Features
L. Sealer		- Compute Intensive Application - HPC, Data Center, Enterprise Server - Hyperscale / Hyperconverged
		Four hot-pluggable systems (nodes) in a 2U form factor. Each node supports the following:
		 Dual AMD EPYC[™] 7001/7002* Series Processors (*AMD EPYC 7002 series drop-in support requires board revision 2.x)
	Super H11DST-B	2. 2TB Registered ECC DDR4 2666MHz SDRAM in 16 DIMMs (700
		Processors) 4TB Registered ECC DDR4 3200MHz SDRAM in 16 DIMMs (Board revision 2.x required + 7002 Processors)
Views: Angled View Node View Front View Rear View	1	 3. 2 PCI-E 3.0 x16 (LP) slot; 1 <u>SIOM</u> card support (flexible networkin Note: must bundle with Network card
Complete System Only : To maintain quality and integrity, this product is sol minimum 2 CPUs, 8 DIMMs, 1 HDD/NVMe and 1 S		4. Integrated IPMI 2.0 + KVM with dedicated LAN • Software Out of Band License key (SFT-OOB-LIC) included for OOB BIOS management
		5. 6 Hot-swap 2.5" NVMe drive bays
vers & Utilities BIOS IPMI Tested Memory Tested M.2 List NVMe Options Tested AOC M	1anuals OS Certification Matrix Quick-References Guide	M.2 Interface: 1 SATA/PCI-E 3.0 x4 M.2 Form Factor: 2280, 22110 M.2 Key: M-key
	6. Video via Aspeed AST2500 BMC	
: Image above may show a varied configuration of optional parts. Please refer	r to parts list for standard parts included.	7. 2600W Redundant Power Supplies Titanium Level (96%) <i>(Full redundancy based on configuration and application load)</i>



Product SKUs - Discontinued SKU (EOL). Please contact sales-rep for alternative options.

A+ Server 2123BT-HNR (**Black**) AS -2123BT-HNR

Motherboard (per Node)

Super H11DST-B

Processor/Chipset (per Node)

- Dual AMD EPYC[™] 7001/7002^{*} series Processors CPU (* Board revision 2.x required) Socket SP3 Supports CPU TDP 200W / cTDP up to 200W**
- Up to 32 Cores (Board revision 1.x + 7001 Processors) Cores Up to 64 Cores (Board revision 2.x + 7002 Processors)
- ** Certain CPUs with high TDP may be supported only under Note specific conditions. Please contact Supermicro Technical Support for additional information about specialized system optimization

System Memory (per Node)

Memory Capacity	16 DIMM slots Supports up to 2TB Registered ECC DDR4 2666MHz SDRAM (7001 Processors) Supports up to 4TB Registered ECC DDR4 3200MHz SDRAM (Board revision 2.x required + 7002 Processors) 8-channel memory bus For Dual CPUs: Recommended that memory be populated equally in adjacent memory banks
Memory Type	DDR4 2666 MHz Registered ECC, 288-pin gold-plated DIMMs (7001 Processors) DDR4 3200 MHz Registered ECC, 288-pin gold-plated DIMMs (Board revision 2.x required + 7002 Processors)
Memory Sizes	8GB, 16GB, 32GB, 64GB, 128GB, 256GB* (* Board revision 2.x required + 7002 processors)
Memory Voltage	1.2V
Error Detection	Corrects single-bit errors Detects double-bit errors (using ECC memory)

On-Board Devices (per Node)

Chipset	System on Chip
Network	Must bundle with at least one <u>SIOM</u> network card

Chassis

Model	CSE-217BHQ+-R2K60BP
Form Factor	2U Rackmount

Width Height Depth Package Weight	17.68" (449mm) 3.47" (88mm) 28.75" (730mm) 24.33" (618mm) H x 9.57" (243mm) W x 45.08" (1145mm) D Gross Weight: 85 lbs (38.6 kg) Net Weight: 54.5 lbs (24.7 kg)
Available Colors	Black
Front Panel (per Node)	
Buttons	Power On/Off button UID button
LEDs	Power status LED HDD activity LED Network activity LEDs Universal Information (UID) LED
Expansion Slots (per Node)	
PCI-Express	2 PCI-E 3.0 (x16) Low-profile slots 1 <u>SIOM</u> card support (must bundle with network card)
M.2	Interface: 1 SATA/PCI-E 3.0 x4 Form Factor: 2280, 22110 Key: M-key
Drive Bays (per Node)	
Hot-swap	6 Hot-swap 2.5" NVMe drive bays Note: NVMe Gen4 drives may only operate at Gen3 speed
System Cooling	
Fans	4 Heavy duty 8cm PWM fans

AC/DC240V Input Redundant Power Supply

2600W Redundant Power Supplies with PMBus

IPMI	Support for Intelligent Platform Management Interface v.2.0	Total Output Power	2600W
	IPMI 2.0 with virtual media over LAN and KVM-over-LAN support	Dimension (W x H x L)	45 x 40 x 480 mm
Video	ASPEED AST2500 BMC	Input	208-240Vac/15-12.5A / 50-60Hz 220-240Vdc/13.5-12.5A (CQC only)
Input / Output (per Node)		+12V	Max: 216.6A / Min: 0A
LAN	Provided via SIOM (optional)	12Vsb	Max: 4.5A / Min: 0A
	1 RJ45 Dedicated IPMI LAN port	Output Type	Gold Finger (4HP+2LP-20S output connector)
USB	2 USB 3.0 ports (rear)	Certification	I Cert. in progress]
Video	1 VGA port		[Cert. in progress]
DOM	1 Super <u>DOM</u> (Disk on Module) port	Operating Environment	
Others	1 COM port (header)	Operating Environment	
	1 TPM 2.0 header	RoHS	RoHS Compliant
System BIOS (per Node)		Environmental Spec.	Operating Temperature: 10°C ~ 30°C (50°F ~ 86°F)
BIOS Type	AMI 128Mb SPI Flash ROM		* Support for operating above 30°C is available in certain
Management (per Node)			system configurations. Contact your Supermicro sales rep or Technical Support for more details.
Software Power Configurations	IPMI 2.0 KVM with dedicated LAN SSM, SUM SuperDoctor® 5 Watch Dog ACPI / APM Power Management		Non-operating Temperature: -40°C to 60°C (-40°F to 140°F) Operating Relative Humidity: 8% to 90% (non-condensing) Non-operating Relative Humidity: 5% to 95% (non-condensing)

Parts List ï,,†

Parts List -	(Items I	ncluded)
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	Part Number	Qty	Description
Motherboard / Chassis	MBD-H11DST-B CSE-217BHQ+-R2K60BP	4 1	Super H11DST-B Motherboard 2U Chassis
Backplane	BPN-ADP-6NVME3-1UB	4	6x NVMe ports and 50A power sourcing daughter card for Big Twin
Backplane	BPN-NVME3-217BHQ	1	2U 24-Port 4-Node NVMe Backplane Support 6x2.5
Cable 1	CBL-PWCD-0376-IS	2	PWCD,US,IEC60320 C19 TO C20,940mm (3ft),14AWG,15A,250V,Black
Drive Tray(s)	MCP-220-00127-0B-BULK	24	Black gen3 Hotswap 2.5 NVMe drive tray, Orange tab/Lock/Bulk
Parts	MCP-240-21721-0N	1	217B BigTwin type I (Impact) BPN retention bkt assy
Riser Card	RSC-P-6	4	RSC-P-6 (1U LHS TwinPro RSC with 1 PCI-Ex16),RoHS
Riser Card	RSC-R1UTP-E16R	4	1U RHS TwinPro Riser card with one PCI-E x16 slot
Software	SFT-OOB-LIC	4	License key for enabling OOB BIOS management
Heatsink / Retention	SNK-P0062PM	4	1U Passive Front CPU Heat Sink w/ a 30-mm Wide Middle Air Channel for AMD H11 2U4N Big Twin Series Servers
Heatsink / Retention	SNK-P0062PW	4	1U Proprietary 93-mm Wide Passive Rear CPU Heat Sink for AMD H11 2U4N Big Twin Series Server
Power Supply	PWS-2K60A-1R	2	1U 1400W/2600W Redundant Titanium PWS, 45(W) X 40(H) X 480(L)
FAN	FAN-0183L4	4	80x80x38 mm, 16.5K RPM, Non-hot-swappable Middle Cooling Fan for X11 Twin Pro, X10 and X11 Big Twin Series Servers

Optional Parts List			
	Part Number	Qty	Description
Global Services & Support	<u>OS4HR3/2/1</u>	-	3/2/1-year onsite 24x7x4 service
	<u>OSNBD3/2/1</u>	-	3/2/1-year onsite NBD service
Software	SFT-DCMS-Single	1	DataCenter Management Package (per node license)
TPM security module	AOM-TPM-9655V	-	TPM 1.2 module with Infineon 9655, RoHS/REACH,PBF;
	<u>AOI</u>	<u>M-TPM-9665V</u> -	TPM 2.0 module with Infineon 9665, RoHS/REACH,PBF;
SIOM	-	-	Supermicro SIOM solutions [Details]

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